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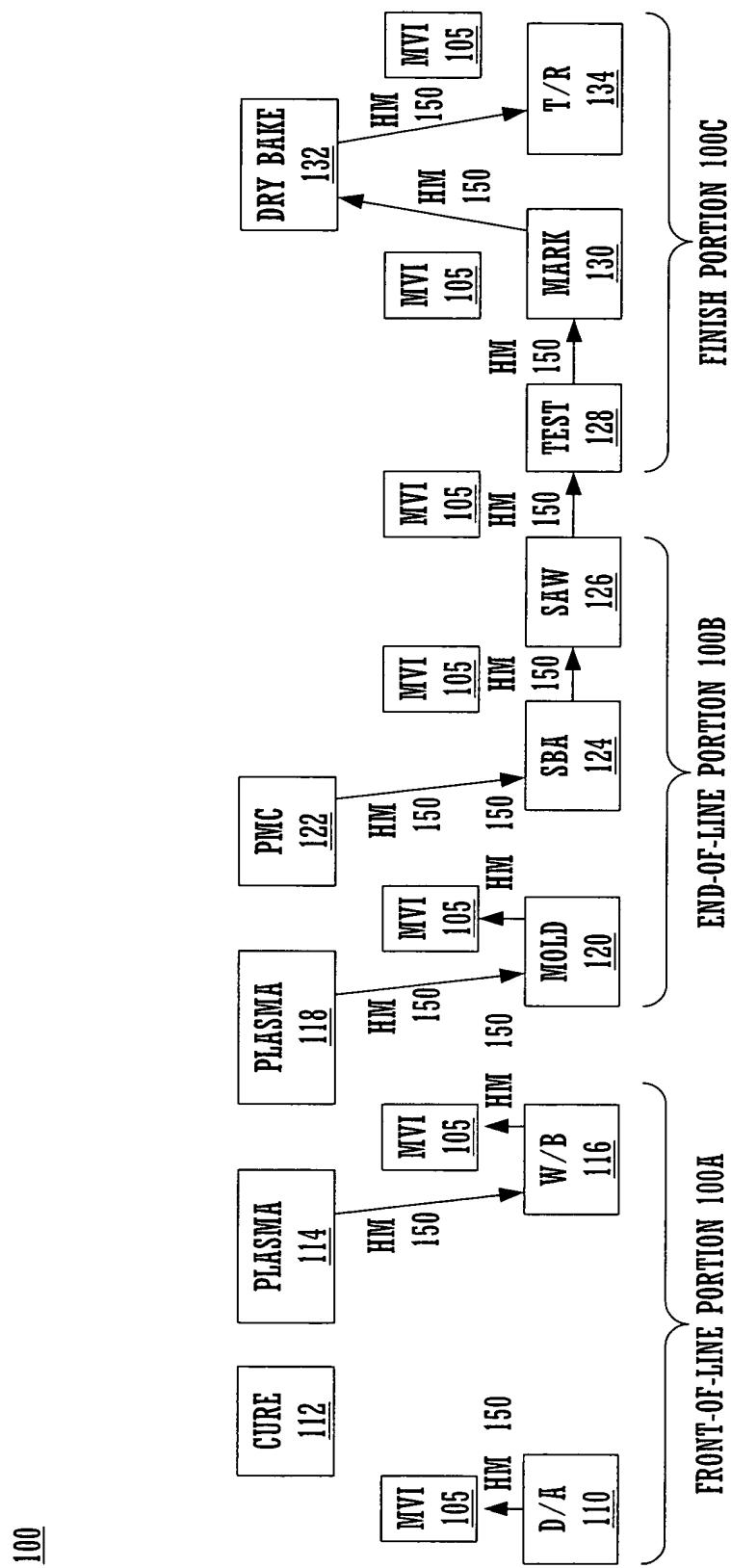
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## FIGURE 1



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200

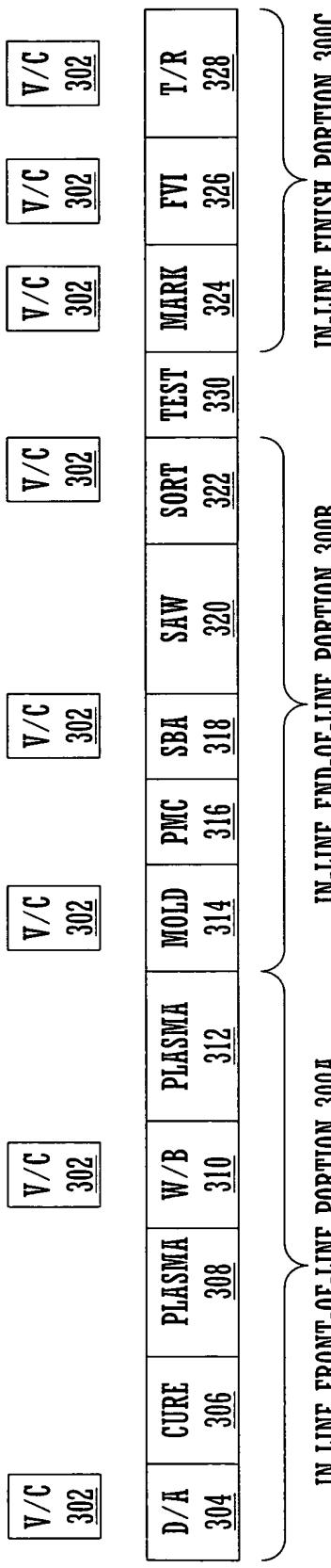


FIGURE 2

TITLE: A METHOD AND SYSTEM FOR UNIVERSAL PACKAGING IN CONJUNCTION WITH A BACK-END  
INTEGRATED CIRCUIT MANUFACTURING PROCESS  
INVENTOR(S): Bo Soon Chang and Vani Verma  
USSN: 10/086,050 ATTORNEY DOCKET #: CYPR-PM01032



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IN-LINE FRONT-OF-LINE PORTION  
300A

V/C  
302

D/A  
304

	CURE	PLASMA	W/B	PLASMA
	<u>306</u>	<u>308</u>	<u>310</u>	<u>312</u>

FIGURE 3A



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IN-LINE END-OF-LINE PORTION  
300B

V/C  
302

V/C  
302

V/C  
302

MOLD	PMC <u>316</u>	SBA <u>318</u>	SAW <u>320</u>	SORT <u>322</u>
<u>314</u>				

FIGURE 3B

TITLE: A METHOD AND SYSTEM FOR UNIVERSAL PACKAGING IN CONJUNCTION WITH A BACK-END  
INTEGRATED CIRCUIT MANUFACTURING PROCESS

INVENTOR(S): Bo Soon Chang and Vani Verma  
USSN: 10/086,050 ATTORNEY DOCKET #: CYPR-PM01032



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IN-LINE FINISH PORTION  
300C

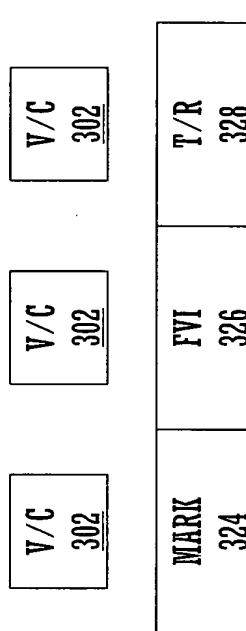


FIGURE 3C



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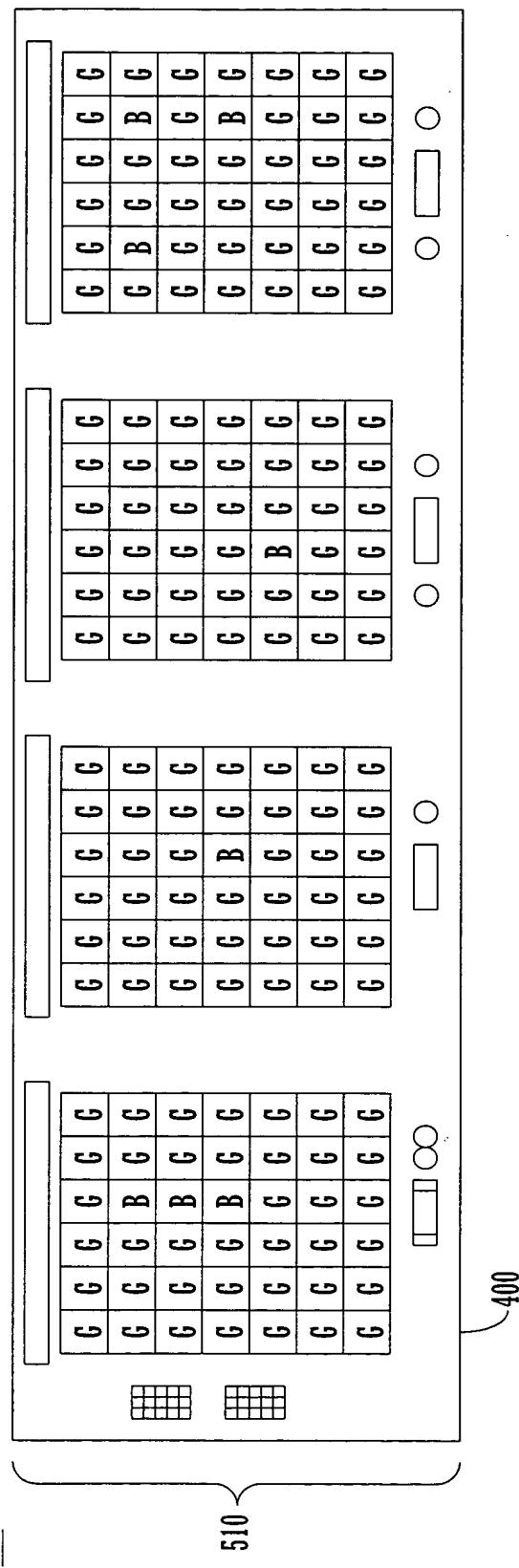
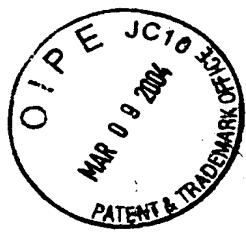


FIGURE 4



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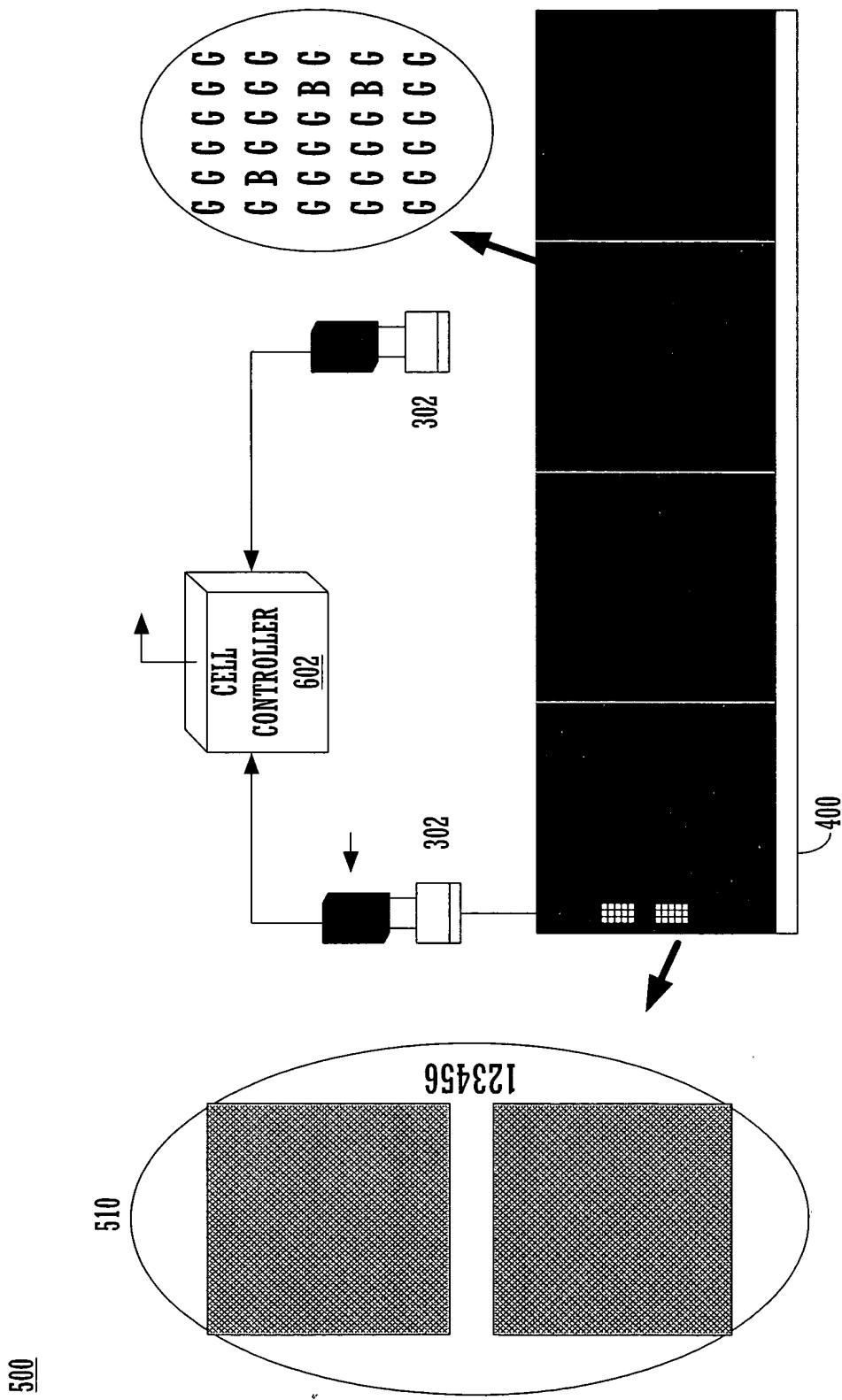
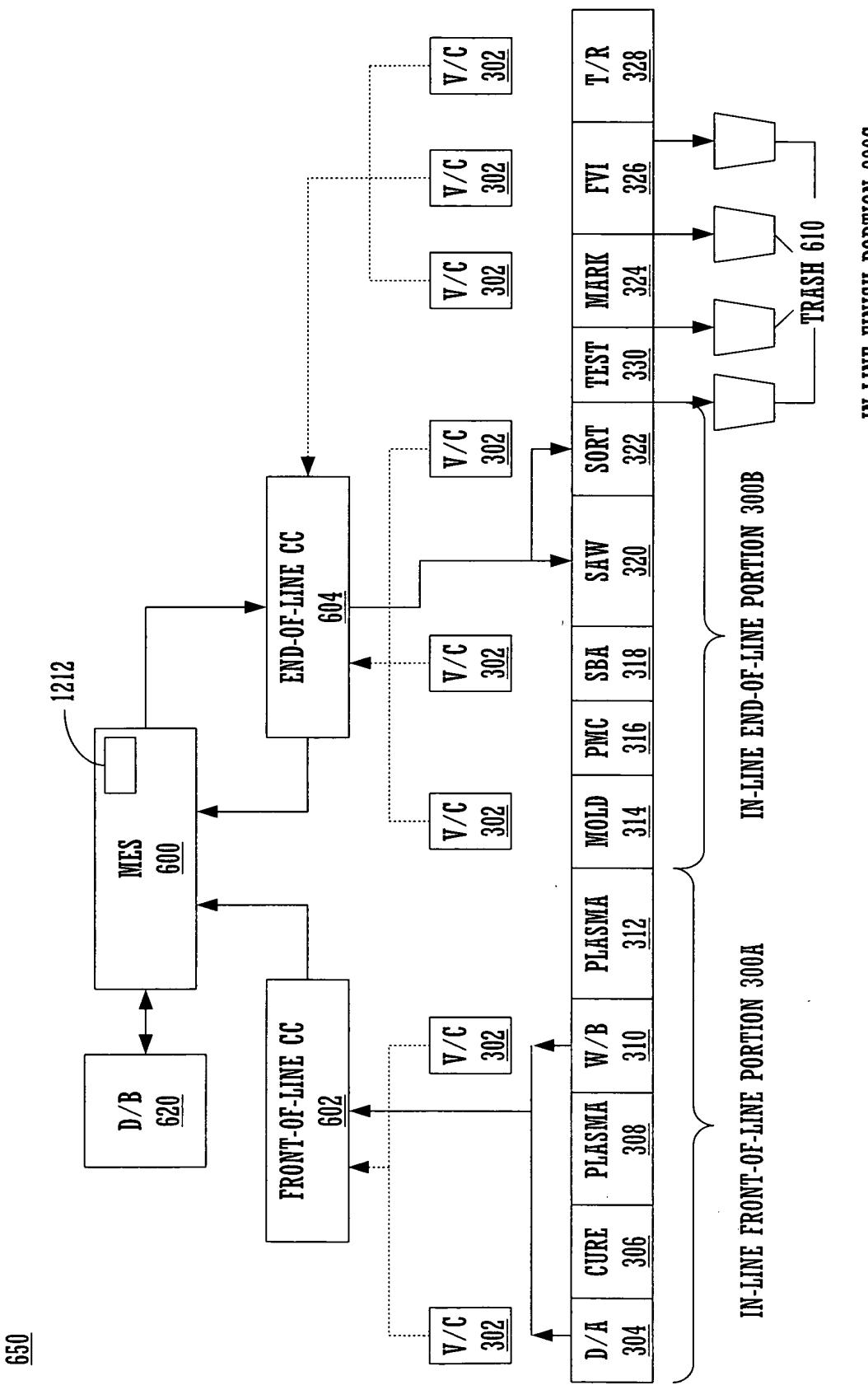


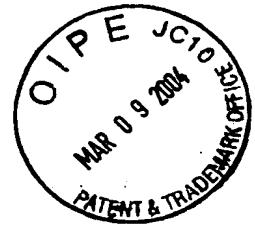
FIGURE 5



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## FIGURE 6



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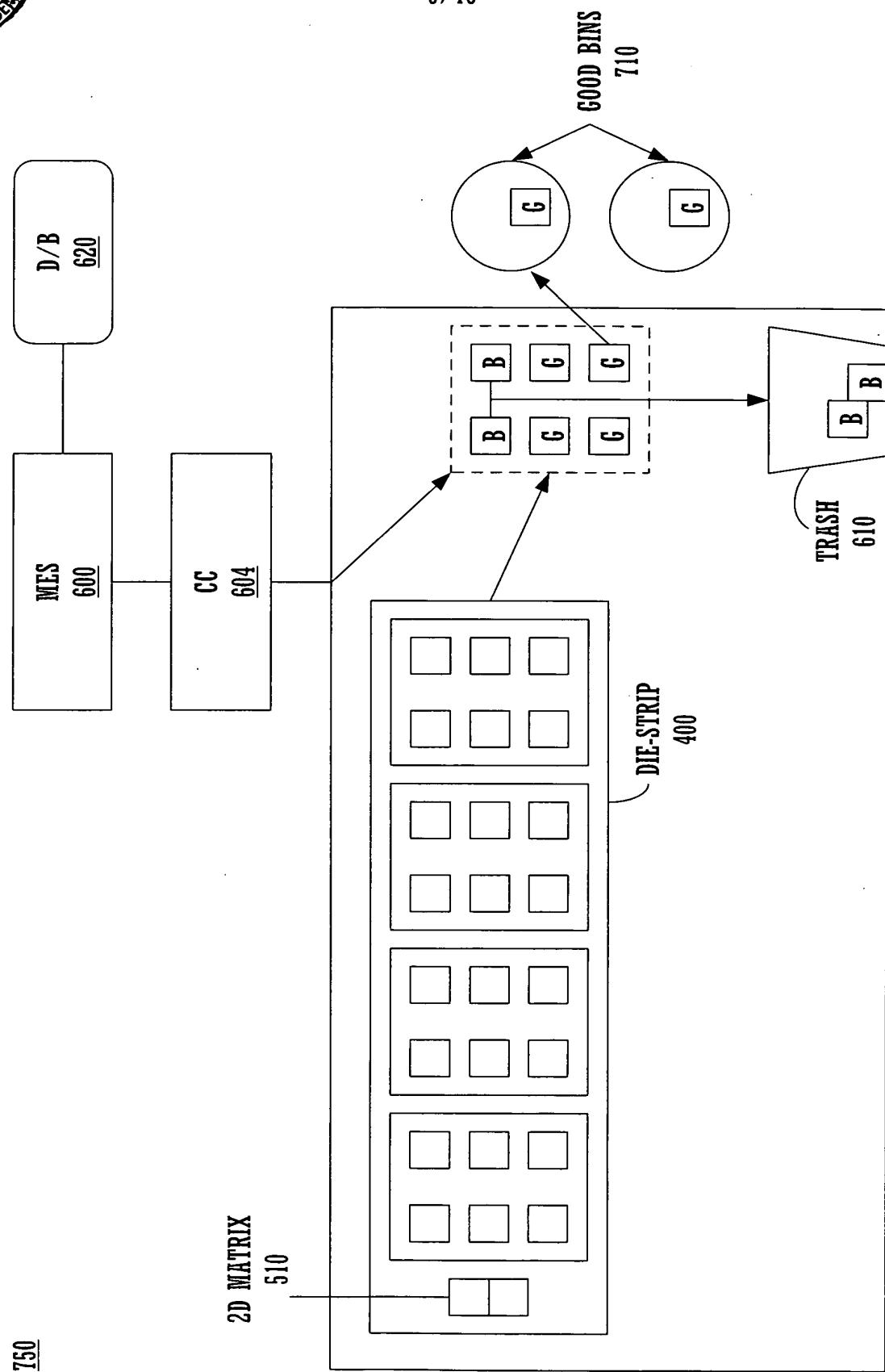
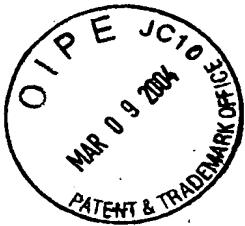


FIGURE 7



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800

START

PROCESSING A DIE-STRIP THROUGH A FRONT-OF-LINE ASSEMBLY PORTION WHICH  
COMPRISES A PLURALITY OF SUB-STATIONS OPERATING ON AN IN-LINE BASIS.

802

AUTOMATICALLY PROVIDING THE DIE-STRIP TO AN END-OF-LINE ASSEMBLY  
PORTION.

804

PROCESSING THE DIE-STRIP BY THE END-OF-LINE ASSEMBLY PORTION WHICH  
COMPRISES A PLURALITY OF SUB-STATIONS OPERATING ON AN IN-LINE BASIS.

806

AUTOMATICALLY PROVIDING THE DIE-STRIP TO A TEST ASSEMBLY PORTION.

808

TESTING THE DIE-STRIP USING THE TEST ASSEMBLY PORTION.

810

AUTOMATICALLY PROVIDING THE DIE-STRIP TO A FINISH ASSEMBLY PORTION.

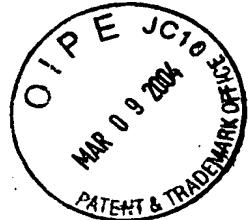
812

PROCESSING THE DIE-STRIP BY THE FINISH ASSEMBLY PORTION WHICH  
COMPRISES A PLURALITY OF SUB-STATIONS OPERATING ON AN IN-LINE BASIS.

814

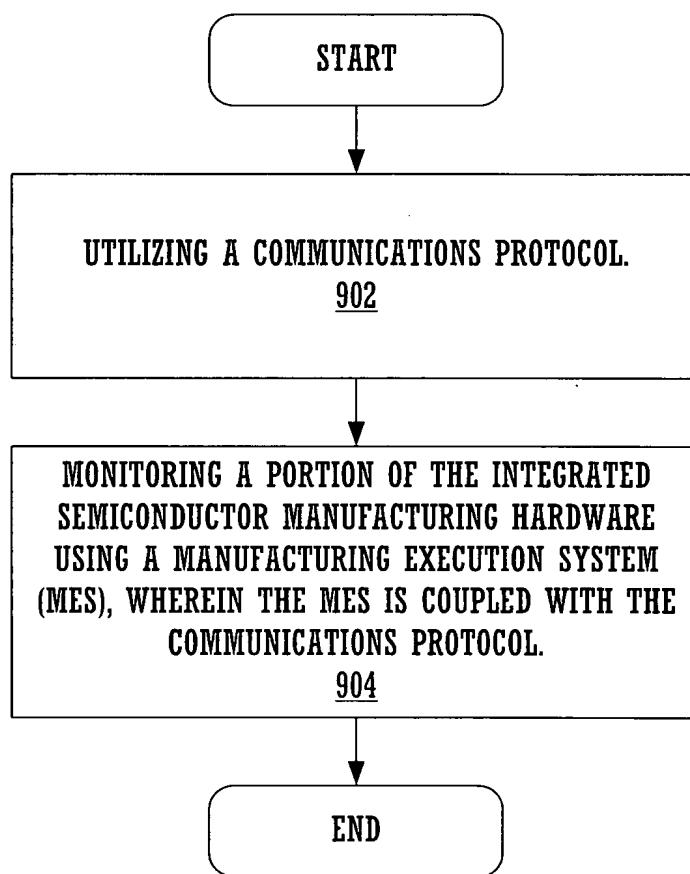
END

FIGURE 8



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**FIGURE 9**



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1000

START

IMPLEMENTING A TRACKING PROCESS FOR THE DIE-STRIP WHICH  
IDENTIFIES INDIVIDUAL DIE-STRIPS AND THEIR RESPECTIVE LOCATIONS  
AS THEY TRAVERSE THROUGH THE IN-LINE ASSEMBLY LINE.

1002

ACCESSING AN ELECTRONIC DIE-STRIP MAP DATABASE THAT  
PROVIDES PARAMETER STORAGE FOR EACH INDIVIDUAL  
SEMICONDUCTOR COMPONENT WITHIN EACH DIE-STRIP.

1004

UTILIZING THE TRACKING PROCESS TO UPDATE THE ELECTRONIC DIE-  
STRIP MAP DATABASE AT EACH SUBSTATION THAT COLLECTS  
PARAMETER INFORMATION.

1006

CATEGORIZING THE DIE ON THE DIE-STRIP BASED ON INFORMATION  
MAINTAINED BY THE ELECTRONIC DIE-STRIP MAP DATABASE AND  
SPECIFICALLY REJECTING BAD DIE AND USING PARAMETER  
INFORMATION TO SORT DIE.

1008

END

FIGURE 10



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1100

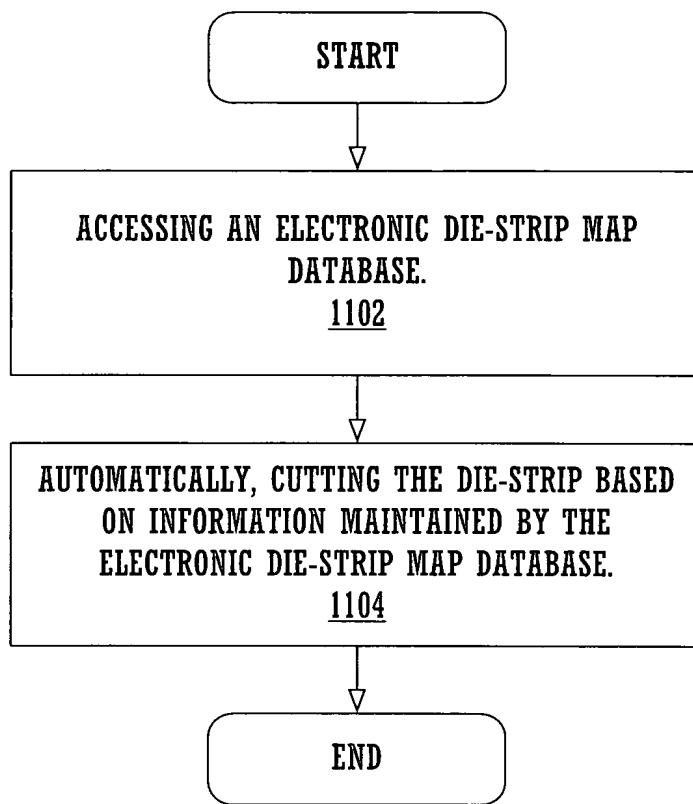
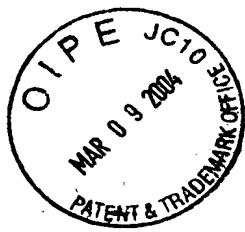


FIGURE 11



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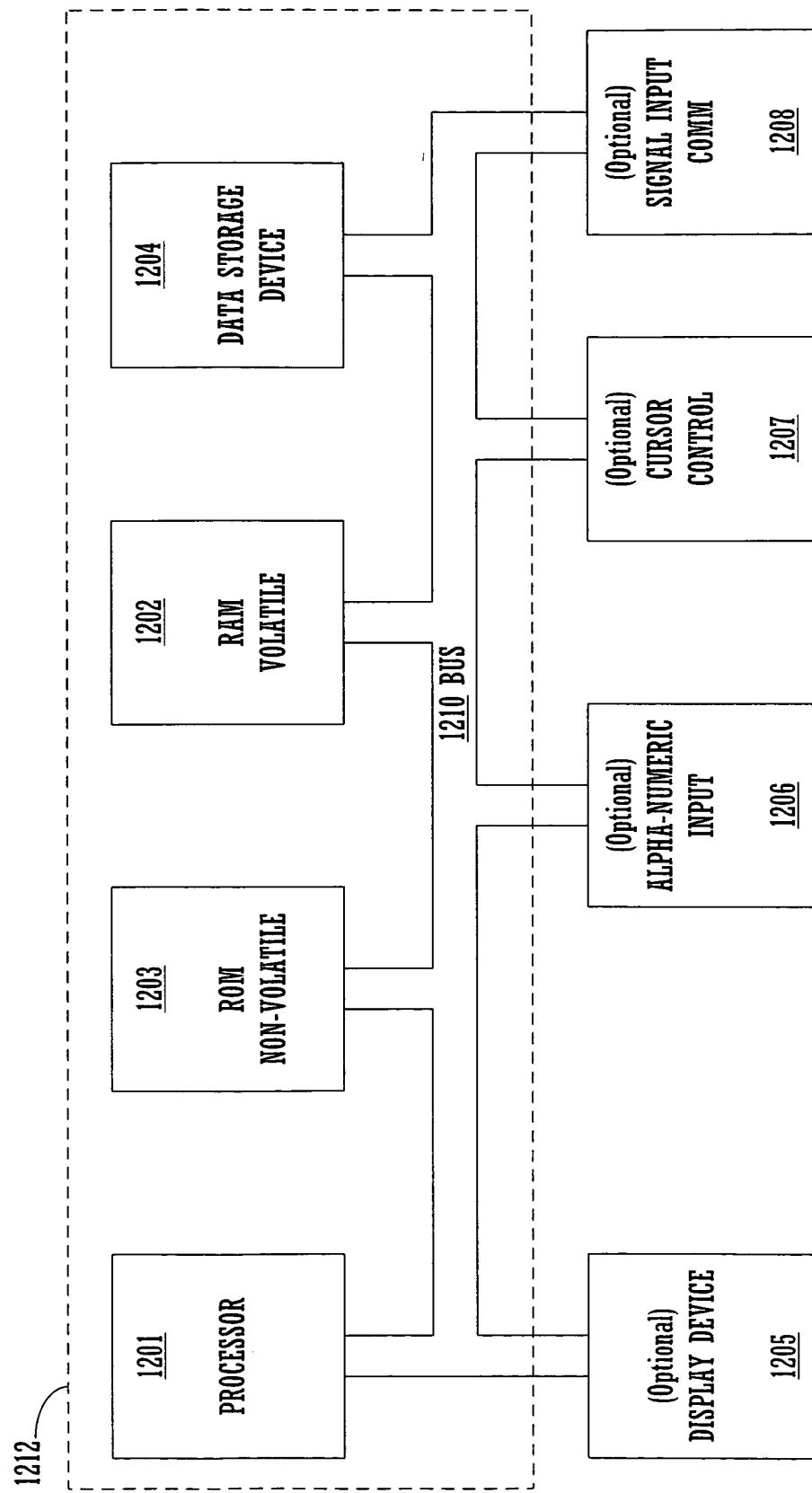


FIGURE 12



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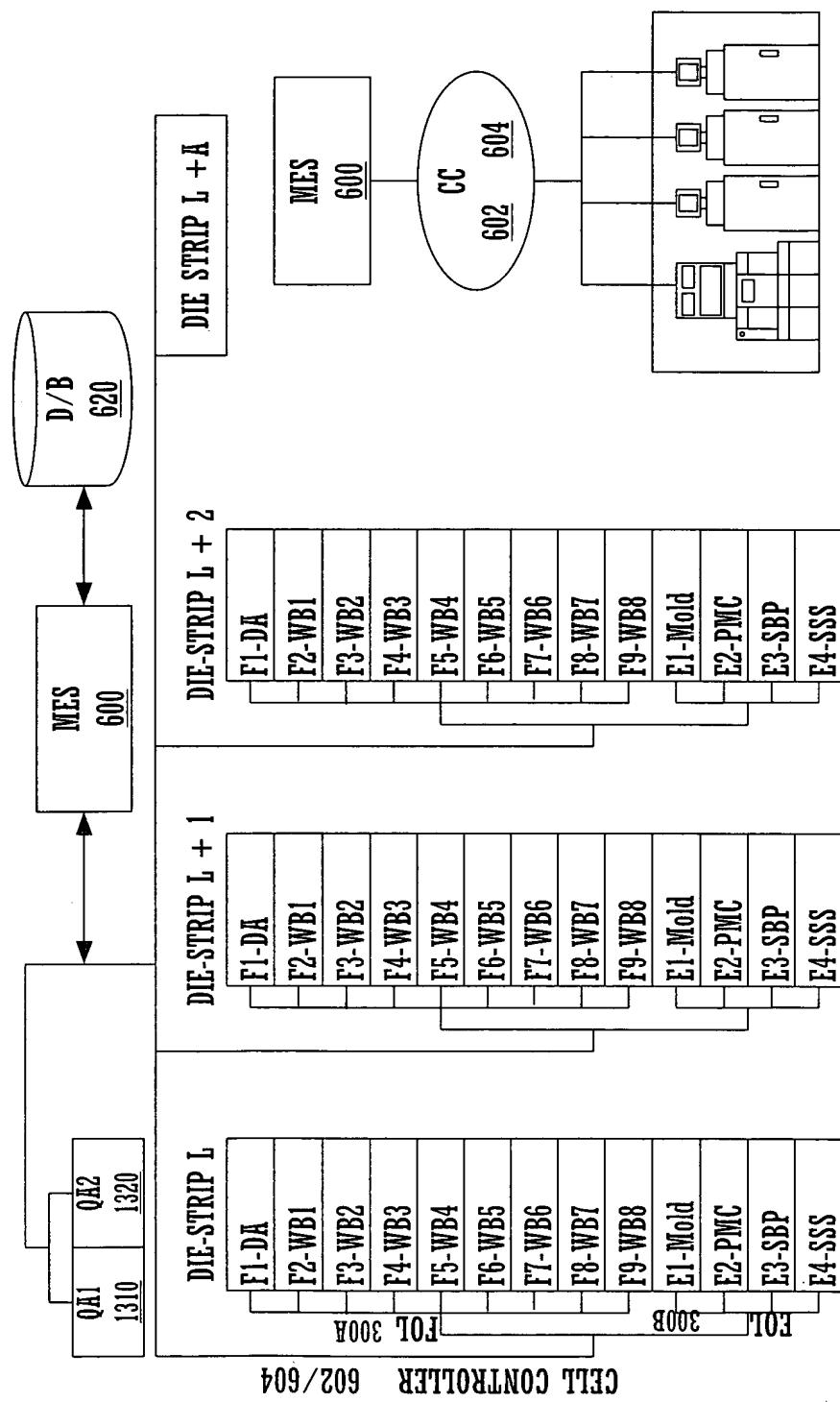


FIGURE 13